

LEXANTM FR RESIN LC108

DESCRIPTION

LEXAN LC108 compound is based on Polycarbonate (PC) resin containing 8% carbon fiber. Added features of this grade include: Electrically Conductive, Flame Retardant.

| GENERAL INFORMATION | |
|-----------------------|---|
| Features | Flame Retardant, Electrically Conductive, Carbon fiber filled, High stiffness/Strength, No PFAS intentionally added |
| Fillers | Carbon Fiber |
| Polymer Types | Polycarbonate (PC) |
| Processing Techniques | Injection Molding |

| INDUSTRY | SUB INDUSTRY |
|----------------------------|-----------------------|
| Electrical and Electronics | Electronic Components |
| Industrial | Material Handling |

TYPICAL PROPERTY VALUES

Revision 20231109

| PROPERTIES | TYPICAL VALUES | UNITS | TEST METHODS |
|---|---------------------|-------|----------------------|
| MECHANICAL ⁽¹⁾ | | | |
| Tensile Stress, yield | 98 | MPa | SABIC - Japan Method |
| Tensile Strain, break | 4 – 6 | % | SABIC - Japan Method |
| Flexural Stress | 160 | MPa | ASTM D790 |
| Flexural Modulus | 5980 | MPa | ASTM D790 |
| Hardness, Rockwell M | 88 | - | ASTM D785 |
| IMPACT ⁽¹⁾ | | | |
| Izod Impact, notched, 23°C | 88 | J/m | ASTM D256 |
| THERMAL ⁽¹⁾ | | | |
| HDT, 0.45 MPa, 3.2 mm, unannealed | 142 | °C | ASTM D648 |
| CTE, -30°C to 30°C | 0.000035 – 0.000059 | 1/°C | ТМА |
| PHYSICAL ⁽¹⁾ | | | |
| Specific Gravity | 1.22 | - | ASTM D792 |
| Water Absorption, (23°C/24hrs) | 0.13 | % | ASTM D570 |
| Mold Shrinkage, flow, 3.2 mm ⁽²⁾ | 0.2 – 0.4 | % | SABIC method |
| ELECTRICAL ⁽³⁾ | | | |
| Surface Resistivity ⁽⁴⁾ | 1.E+08 – 1.E+12 | Ω | ASTM D257 |
| INJECTION MOLDING (3) | | | |
| Drying Temperature | 120 | °C | |
| Drying Time | 4 – 6 | Hrs | |
| Maximum Moisture Content | 0.02 | % | |
| Melt Temperature | 290 – 320 | °C | |
| Nozzle Temperature | 285 – 315 | °C | |

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CHEMISTRY THAT MATTERS



| PROPERTIES | TYPICAL VALUES | UNITS | TEST METHODS |
|-------------------------------------|----------------|-------|--------------|
| Front - Zone 3 Temperature | 290 – 320 | °C | |
| Middle - Zone 2 Temperature | 280 - 310 | °C | |
| Rear - Zone 1 Temperature | 270 – 300 | °C | |
| Mold Temperature | 100 – 125 | °C | |
| Back pressure (Plastic Pressure) | 3 – 8 | MPa | |
| Screw speed (Circumferential speed) | 0.1 – 0.2 | m / s | |
| Shot to Cylinder Size | 30 – 70 | % | |

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.

(3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

(4) Measurement meets requirements as specified in ASTM D4496.

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